

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1147	blister and ((electron or ion) adj beam)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 11:05
L2	133	blister and ((electron or ion) adj beam) and implanted	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 11:06
L3	68	blister and ((electron or ion) adj beam) and implanted and pattern	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 11:06
L6	2	("6197697").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/14 11:21
L7	6	((("6197697") or ("6225193") or ("4843238"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/14 11:23
L8	3	(US-4843238-\$ or US-6197697-\$ or US-6225193-\$).did.	USPAT	ADJ	ON	2008/03/14 11:25
L9	3	blister and ((electron or ion) adj beam) and implanted and pattern and L8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 11:25
L10	2	("20060211258").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/14 12:10

L11	2	blister and ((electron or ion) adj beam) and implanted and pattern and L8 AND FILM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:41
L12	1	blister and ((electron or ion) adj beam) and implanted and pattern and L8 AND form with FILM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:41
L13	1	blister and ((electron or ion) adj beam) and implanted and pattern and L8 AND (form or forming or formed) with film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:42
L14	1	blister and ((electron or ion) adj beam) and implanted and adsorption probability	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:45
L15	14	blister and ((electron or ion) adj beam) and implanted and reactiv\$4 with film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:46
L16	1	blister and ((electron or ion) adj beam) and implanted and reactiv\$4 with difference with film	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:47
L17	14	blister and ((electron or ion) adj beam) and implanted and reactiv\$4 with film and chemical	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:48
L18	6	blister and ((electron or ion) adj beam) and implanted and reactiv\$4 with film and chemical adj reaction	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 12:48
L26	3	(US-4843238-\$ or US-6197697-\$ or US-6225193-\$).did.	USPAT	ADJ	ON	2008/03/14 13:42

L27	3	I8 and I26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 13:42
L28	3	I8 or I26	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 13:42
L29	1	(US-4843238-\$).did.	USPAT	ADJ	ON	2008/03/14 13:43
L30	2	@ad<"20030728" and L8 and (blister or (gas adj bubble)) same pattern\$4 and (layer or film or substrate or wafer) same (blister or (gas adj bubble)) and L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 13:43
L31	2	L30 or L29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 13:43
L32	3	L31 or I28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 13:43
L33	1	(US-6407399-\$).did.	USPAT	ADJ	ON	2008/03/14 13:44
L34	1	(US-5660957-\$).did.	USPAT	ADJ	ON	2008/03/14 13:44
L35	5	L31 or I28 or I33 or I34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 13:45
L36	30	blister and ((electron or ion) adj beam) and implanted and (xenon or argon or krypton) with ion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 14:08

L37	0	blister and ((electron or ion) adj beam) and implanted and (xenon or argon or krypton) with ion and I35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 14:08
L38	24	@ad<"20040726" and blister and ((electron or ion) adj beam) and implanted and (xenon or argon or krypton) with ion	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 14:09
L39	7	(("4,843,238") or ("6,407,399") or ("6,225,193") or ("7,038,290")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/14 14:27
L40	9	I35 or I39	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/14 14:27
S2	3600	(250/492.2).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/11 13:44
S3	9726	(250/492.1-492.3).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/11 13:44
S4	405	S3 and pattern\$4 with (two or "2") with dimension\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:45
S5	46	S3 and pattern\$4 with (two or "2") with dimension\$4 and substrate with (electron or ion) with irradiat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:46

S6	132	S3 and pattern\$4 with (two or "2") with dimension\$4 and (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer) with (electron or ion) with irradiat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:47
S7	88	@ad<"20030728" and S3 and pattern\$4 with (two or "2") with dimension\$4 and (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer) with (electron or ion) with irradiat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:48
S10	18	S3 and blister	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:49
S11	12	@ad<"20030728" and S3 and blister	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:49
S13	0	@ad<"20030728" and S3 and blister and pattern\$4 with (two or "2") with dimension\$4 and (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer) with (electron or ion) with irradiat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:50
S14	0	@ad<"20030728" and S3 and blister and pattern\$4 with (two or "2") with dimension\$4 and (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:50

S15	0	@ad<"20030728" and S3 and blister and pattern\$4 with (two or "2") with dimension\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:50
S16	29	@ad<"20030728" and S3 and (blister or bubble) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:52
S17	0	@ad<"20030728" and S3 and (blister or bubble) with ("2" or two) with dimension\$4 with pattern \$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:52
S18	0	@ad<"20030728" and S3 and (blister or bubble) same ("2" or two) with dimension\$4 with pattern \$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:52
S19	22	@ad<"20030728" and S3 and (blister or bubble or defect) same ("2" or two) with dimension\$4 with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:53
S20	15	@ad<"20030728" and S3 and (blister or bubble or defect) same ("2" or two) with dimension\$4 with pattern\$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 13:54
S21	0	@ad<"20030728" and S3 and (blister or bubble) same ("2" or two) with dimension\$4 with pattern \$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:24

S22	0	S3 and (blister or bubble) same ("2" or two) with dimension\$4 with pattern\$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:25
S23	5	S3 and (blister or bubble) and ("2" or two) with dimension\$4 with pattern\$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:25
S24	5	S3 and (blister or bubble) and (((("2" or two) with dimension\$4) or ("2" or two)?dimension\$4) with pattern\$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:27
S25	826	(blister or bubble) and (((("2" or two) with dimension\$4) or ("2" or two)?dimension\$4) with pattern\$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:29
S26	2	S2 and (blister or bubble) and (((("2" or two) with dimension\$4) or ("2" or two)?dimension\$4) with pattern\$4 and (blister or bubble or defect) with (specimen or sample or surface or film or target or substrate or subject or workpiece or article or object or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:30

S27	0	S3 and (blister) and (((("2" or two) with dimension\$4) or ("2" or two)?dimension\$4) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:32
S28	0	S3 and (blister) and (("2" or two) with dimension\$4) or ("2" or two)?dimension\$4) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:32
S29	405	S3 and (("2" or two) with dimension\$4) or ("2" or two)?dimension\$4) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:33
S30	2	S3 and blister with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:33
S31	33	S3 and (bubble or blister) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 14:34
S32	29	@ad< "20030728" and S3 and (bubble or blister) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 15:46
S33	24	@ad< "20030728" and S3 and (bubble or blister) with pattern\$4 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 15:50
S34	1	@ad< "20030728" and S3 and (bubble or blister) with pattern\$4 and substrate with blister	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 15:53

S35	10	@ad<"20030728" and S3 and (bubble or blister) with pattern\$4 and substrate with (bubble or blister)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 15:58
S36	1	(US-4843238-\$).did.	USPAT	ADJ	ON	2008/03/11 16:05
S37	1	@ad<"20030728" and S3 and (blister) with pattern \$4 and substrate with (blister)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 16:05
S38	1	@ad<"20030728" and S3 and (blister) same pattern \$4 and substrate with (blister)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 16:05
S40	3	@ad<"20030728" and S3 and (blister) same pattern \$4 and substrate same (blister)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 16:06
S41	4	@ad<"20030728" and S3 and (blister) same pattern \$4 and (layer or film or substrate) same (blister)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/11 18:42
S42	9726	(250/492.1-492.3).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/12 11:53
S43	4	@ad<"20030728" and S42 and (blister or (gas adj bubble)) same pattern \$4 and (layer or film or substrate) same (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 11:53
S44	4	@ad<"20030728" and S42 and (blister or (gas adj bubble)) and pattern \$4 and (layer or film or substrate) same (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 11:56

S45	3028	@ad<"20030728" and (blister or (gas adj bubble)) and pattern\$4 and (layer or film or substrate or wafer) same (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:07
S46	595	@ad<"20030728" and (blister or (gas adj bubble)) same pattern\$4 and (layer or film or substrate or wafer) same (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:07
S47	430	@ad<"20030728" and (blister or (gas adj bubble)) same pattern\$4 and (layer or film or substrate or wafer) with (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:08
S48	7	@ad<"20030728" and (blister or (gas adj bubble)) same pattern\$4 and (layer or film or substrate or wafer) with (blister or (gas adj bubble)) and (((2" or two) with dimension\$4) or (2" or two)?dimension\$4) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:09
S49	147058	("250").CLAS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/12 12:10
S50	0	@ad<"20030728" and S49 and (blister or (gas adj bubble)) same pattern\$4 and (layer or film or substrate or wafer) with (blister or (gas adj bubble)) and (((2" or two) with dimension\$4) or (2" or two)?dimension\$4) with pattern\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:10
S51	7	@ad<"20030728" and S49 and (blister or (gas adj bubble)) same pattern\$4 and (layer or film or substrate or wafer) same (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:10

S52	1	(US-6407399-\$).did.	USPAT	ADJ	ON	2008/03/12 12:31
S53	7	@ad<"20030728" and S49 and (blister or (gas adj bubble)) same pattern \$4 and (layer or film or substrate or wafer or resist) same (blister or (gas adj bubble))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:32
S54	1	@ad<"20030728" and S49 and (blister or (gas adj bubble)) same pattern \$4 and (layer or film or substrate or wafer) same (blister or (gas adj bubble)) and S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/12 12:34
S55	1	(US-4843238-\$).did.	USPAT	ADJ	ON	2008/03/13 11:19
S56	1	@ad<"20030728" and L8 and (blister or (gas adj bubble)) same pattern \$4 and (layer or film or substrate or wafer) same (blister or (gas adj bubble)) and L9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/13 11:24
S57	2	S56 or S55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/03/13 11:25

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